

ABSTRACT

A thin type ball grid array package is provided. A composite substrate for the package is consisted of a wiring board and a dummy die. The wiring board has an opening through upper and lower surfaces thereof. The dummy chip is attached to one surface of the wiring board, and covers the opening to form a chip cavity for accommodating an integrated circuit chip. The wiring board has a step with a plurality of connecting pads in the opening. The integrated circuit chip is attached to the dummy die and electrically connected to the connecting pads of the wiring board. A package body is formed in the chip cavity.